

**INVENTORSHIP DECLARATION BY INVENTOR**

I HEREBY DECLARE THAT:

My residence, mailing address, and citizenship are stated next to my name in PART A hereof.

I believe I am the original, first, and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

**PROCESSES AND TOOLS FOR FORMING LEAD-FREE ALLOY SOLDER PRECURSORS**

the specification of which:

is attached hereto.

was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 CFR §1.56, including, for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim priority benefits under 35 USC §119(a)-(d) or (f), §172, or §365(a)-(b) of any foreign or international application(s) for patent or inventor's certificate listed in PART B hereof and have also identified in PART B hereof any such foreign or international application having a filing date before that of the application of which priority is claimed.

I hereby declare that all statements made herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. I understand that the execution of this document does not in itself establish an attorney-client relationship between the undersigned and Christensen O'Connor Johnson Kindness, PLLC, or any of its attorneys.

See page 2 attached, signed, and made a part hereof.

**INVENTORSHIP DECLARATION BY INVENTOR**

**PART A: INVENTOR INFORMATION AND SIGNATURE**

Full name of inventor: Bioh Kim

Citizenship: Republic of Korea      Mailing Address: 17 Honeysuckle Lane  
Kalispell, MT 59901

Residence (if different): \_\_\_\_\_

Inventor's Signature:       Date: 10/9/03

**INVENTORSHIP DECLARATION BY INVENTOR**

**PART B: CLAIM TO PRIORITY OF FOREIGN APPLICATION(S) UNDER 35 U.S.C. § 119(a-d)  
and (f) § 172, or § 365(a)-(b)**

Country	App. No.	Filing Date	Priority Not Claimed
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: B. Kim

Attorney Docket No.: SEMT116964

Application No.: Filed Concurrently Herewith

Filed: Concurrently Herewith

Title: PROCESSES AND TOOLS FOR FORMING LEAD-FREE ALLOY  
SOLDER PRECURSORS

POWER OF ATTORNEY OF ASSIGNEE AND  
CERTIFICATION UNDER 37 C.F.R. § 3.73(b)

TO THE COMMISSIONER FOR PATENTS:

I, the undersigned, acting on behalf of the Assignee of the entire right, title, and interest in the above-identified patent application, by virtue of an Assignment filed concurrently herewith, appoint the attorneys and agents listed below to prosecute this application and transact all business with the U.S. Patent and Trademark Office in connection therewith. This appointment is to the exclusion of the inventor(s) and their attorney(s) and agent(s) in accordance with the provisions of 37 C.F.R. § 3.71.

All prior powers of attorney for this application are hereby revoked. The Assignee hereby appoints the firm of Christensen O'Connor Johnson Kindness<sup>PLLC</sup> and Lee E. Johnson, Reg. No. 22,946; Gary S. Kindness, Reg. No. 22,178; James W. Anable, Reg. No. 26,827; James R. Uhlir, Reg. No. 25,096; Jerald E. Nagae, Reg. No. 29,418; Dennis K. Shelton, Reg. No. 26,997; Jeffrey M. Sakoi, Reg. No. 32,059; Ward Brown, Reg. No. 28,400; Robert J. Carlson, Reg. No. 35,472; Rodney C. Tullett, Reg. No. 34,034; Daiva K. Tautvydas, Reg. No. 36,077; Maria L. C. Anderson, Reg. No. 40,574; George E. Renzoni, Ph.D., Reg. No. 37,919; Philip P. Mann, Reg. No. 30,960; George S. Farber, Reg. No. 41,497; Kevan L. Morgan, Reg. No. 42,015; John D. Denkenberger, Reg. No. 44,060; and Melanie J. Seelig, Reg. No. 44,328; members of the firm, with full power to prosecute said application and to transact all business in the United States Patent and Trademark Office connected therewith. Address all telephone calls to Jeffrey M. Sakoi at telephone number 206.695.1713.

I also hereby grant the following attorney a principal power of attorney with full power to prosecute this application and transact all business the U.S. Patent and Trademark Office connected therewith: Harry M. Cross, Jr., Reg. No. 22,229.

LAW OFFICES OF  
CHRISTENSEN O'CONNOR JOHNSON KINDNESS<sup>PLLC</sup>  
1420 Fifth Avenue  
Suite 2800  
Seattle, Washington 98101  
206.682.8100

Address all further correspondence relating to said application to:

**Customer No. 26389**

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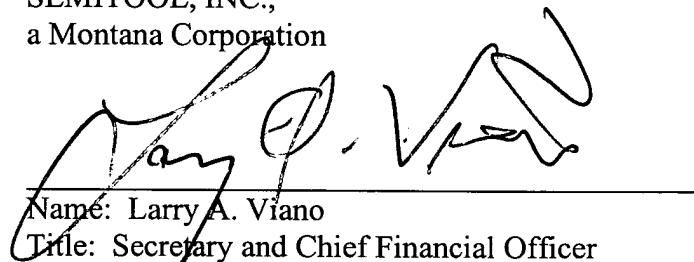
In accordance with 37 C.F.R. § 3.73(b), I hereby certify that I am empowered to act on behalf of Assignee. To the best of my knowledge and belief, title is in the Assignee, as evidenced by the Assignment noted above.

I further declare that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent resulting therefrom.

Respectfully submitted,

SEMITOOL, INC.,  
a Montana Corporation

Date: 10/10/03



Name: Larry A. Viano  
Title: Secretary and Chief Financial Officer

JMS:mxc

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